BB02-CX

CUSTOMER PRODUCT SPECIFICATION SHEET

BB02-CX : 1.27mm x 1.27mm (0.05" x 0.05") SOCKET, RIGHT ANGLE, SMT, DUAL ROW - 04 TO 80 CONTACTS

SPECIFICATIONS:
- CURRENT RATING: 1 AMPS
- INSULATOR RESISTANCE: 1000 MEGOHMS MIN.
- DIELECTRIC WITHSTANDING: AC 500V
- OPERATING TEMPERATURE: -40°C TO +105°C
- CONTACT MATERIAL: PHOSPHOR BRONZE
- INSULATOR MATERIAL: THERMOPLASTIC, UL 94V-0
- STANDARD: LCP+30% G/F

PLATING:
- GOLD OR TIN OVER 30-500U NICKEL

SOLDERABILITY:
- IR REFLOW: 280°C FOR 10 SEC
- MANUAL SOLDER: 380°C FOR 3-5 SEC

NOTES:
1. RECOMMENDED MATING PIN LENGTH: 3.5MM.
2. PARTS WITH SMALL PIN NUMBERS MIGHT BE PACKED IN BOX INSTEAD OF TUBE.

MATES WITH:
BB02-BC
BB02-BK
BB02-6P
BB02-6S

HOW TO ORDER

BB02 - EXXXZ - XX0 - 0000000

CONTACT PLATING OPTIONS:
- K = GOLD FLASH (STANDARD)
- A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL
- B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL
- C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL
- T = BRIGHT TIN
- M = MATT TIN

PACKAGING OPTIONS:
- 3 = TUBE
- 6 = TAPE & PEEL

(SEEN NOTE 2)

RECOMMENDED PCB BOARD SMD LAYOUT
(TOLERANCE: ±0.05)

Scale: 5/1
Third Angle: RIGHT
Material: SEE NOTE

Type: BB02-CX
Date: 30 AUG '18
Revision: 1.6
Unit: mm

For drawings controlling or referencing this drawing, see www.gradconn.com

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